

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Applicant proposes to amend claims 54 and 58, and add new claims 59-63 as follows:

Listing of Claims:

1-53. (Cancelled)

54. (Currently Amended) A method for removing material from a microelectronic substrate, comprising:

providing a substrate holder that carries the microelectronic substrate and at least one membrane having a first membrane portion and a second membrane portion, the at least one membrane disposed between the substrate holder and the microelectronic substrate;

engaging the microelectronic substrate with a planarizing medium;

moving at least one of a first part of the microelectronic substrate and a first portion of the planarizing medium relative to the other at a first rate;

moving at least one of a second part of the microelectronic substrate and the first portion of the planarizing medium relative to the other at a second rate less than the first rate;

advancing the ~~polishing~~ planarizing medium from a supply roller to a take up roller to engage a second portion of the ~~polishing~~ planarizing medium with the first and second parts of the microelectronic substrate; and

removing material from the first and second parts of the microelectronic substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with a the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with a the second membrane portion having a second thickness greater than the first thickness.

55. (Original) The method of claim 54 wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad.

56. (Original) The method of claim 54 wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

57. (Cancelled)

58. (Currently Amended) The method of claim 54 wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

59. (Cancelled)

60. (New) A method for removing material from a microelectronic substrate, comprising:

providing a substrate holder that carries the microelectronic substrate and at least one membrane having a first membrane portion and a second membrane portion, the at least one membrane disposed between the substrate holder and the microelectronic substrate;

engaging the microelectronic substrate with a planarizing medium;

moving at least one of a first part of the microelectronic substrate and the planarizing medium relative to the other at a first rate;

moving at least one of a second part of the microelectronic substrate and the planarizing medium relative to the other at a second rate less than the first rate; and

removing material from the first and second parts of the microelectronic substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with the second membrane portion having a second thickness greater than the first thickness.

61. (New) The method of claim 60 wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad.

62. (New) The method of claim 60 wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

63. (New) The method of claim 60 wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

64. (New) The method of claim 60 wherein biasing the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller

to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.